

Title (en)

INTEGRATED CHEMICAL MECHANICAL POLISHING COMPOSITION AND PROCESS FOR SINGLE PLATEN PROCESSING

Title (de)

ZUSAMMENSETZUNG ZUM INTEGRIERTEN CHEMISCH-MECHANISCHEN POLIEREN UND VERFAHREN ZUR EINZELPLATTENBEHANDLUNG

Title (fr)

COMPOSITION DE POLISSAGE CHIMICO-MECANIQUE INTEGRE ET PROCEDE POUR TRAITER UNE PLATINE INDIVIDUELLE

Publication

EP 1899111 A2 20080319 (EN)

Application

EP 06772376 A 20060606

Priority

- US 2006022037 W 20060606
- US 68772105 P 20050606

Abstract (en)

[origin: WO2006133249A2] Chemical mechanical polishing (CMP) compositions and single CMP platen process for the removal of copper and barrier layer material from a microelectronic device substrate having same thereon. The process includes the in situ transformation of a Step I slurry formulation, which is used to selectively remove and planarize copper, into a Step II slurry formulation, which is used to selectively remove barrier layer material, on a single CMP platen pad.

IPC 8 full level

B44C 1/22 (2006.01); **C23F 1/00** (2006.01); **C23F 1/10** (2006.01); **H01L 21/302** (2006.01)

CPC (source: EP KR US)

B24B 37/00 (2013.01 - KR); **C09G 1/02** (2013.01 - EP KR US); **C09K 3/14** (2013.01 - KR); **C09K 3/1463** (2013.01 - EP US); **C09K 3/1472** (2013.01 - EP US); **H01L 21/321** (2013.01 - KR); **H01L 21/3212** (2013.01 - EP US)

Citation (search report)

See references of WO 2006133249A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA HR MK RS

DOCDB simple family (publication)

WO 2006133249 A2 20061214; **WO 2006133249 A3 20090416**; CN 101511607 A 20090819; EP 1899111 A2 20080319; IL 187914 A0 20080320; JP 2008546214 A 20081218; KR 101332302 B1 20131125; KR 20080016934 A 20080222; TW 200706703 A 20070216; TW I434957 B 20140421; US 2009215269 A1 20090827

DOCDB simple family (application)

US 2006022037 W 20060606; CN 200680028191 A 20060606; EP 06772376 A 20060606; IL 18791407 A 20071205; JP 2008515851 A 20060606; KR 20087000153 A 20060606; TW 95119999 A 20060606; US 91672706 A 20060606